

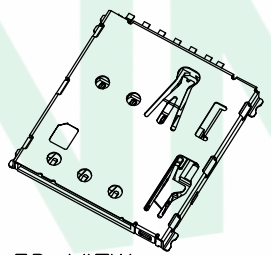
REV.	DESCRIPTION	ECN NO.	NAME	DATE

**NOTES:**

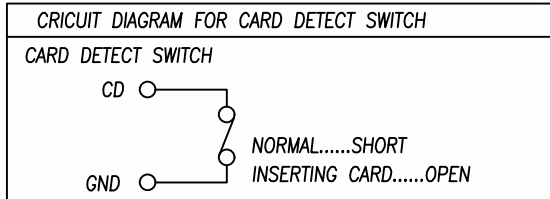
- MATERIAL:**  
 HOUSING: High Temperature Thermoplastic  
 Terminal: Copper Alloy  
 Shell: Stainless Steel
- PLATING:**  
 Terminal: 50u" Ni UNDERPLATED OVERALL  
 G/F PLATED ON CONTACT AREA AND SOLDER AREA  
 Shell: 30u" Ni UNDERPLATED OVERALL  
 G/F PLATED ON CONTACT AREA AND SOLDER AREA
- TECHNICAL SPECIALITY:**  
 RATED VOLTAGE: 30V AC MAX.  
 CURRENT RATING: 0.5A MAX.  
 INSULATION RESISTANCE: 1000MΩ MIN  
 CONTACT RESISTANCE: 50mΩ MAX  
 WITHSTANDING VOLTAGE: 500V AC FOR 1 MINUTES  
 OPERATING TEMPERATURE: -40 ~ +85 Humidity 80% R.H MAX
- DIMENSIONS WITH MARK " \* " MUST BE MEASURE BY QC AND IPQC**

RECOMMENDED PCB LAYOUT TOP VIEW (TOLERANCE: ±0.05)  
 RECOMMENDED MATAL MASK T=0.12mm

- SMT SOLDER AREA
- NO PATTERN AND VIA HOLE IN HTIS AREA



3D VIEW



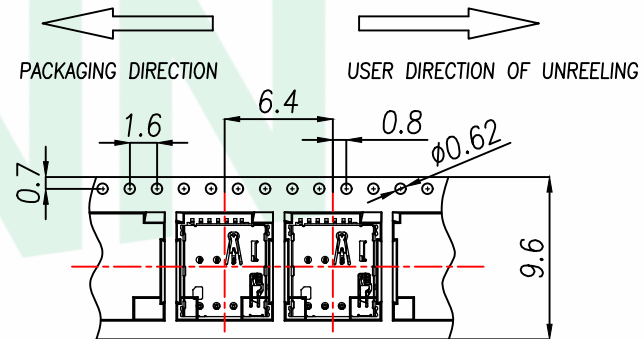
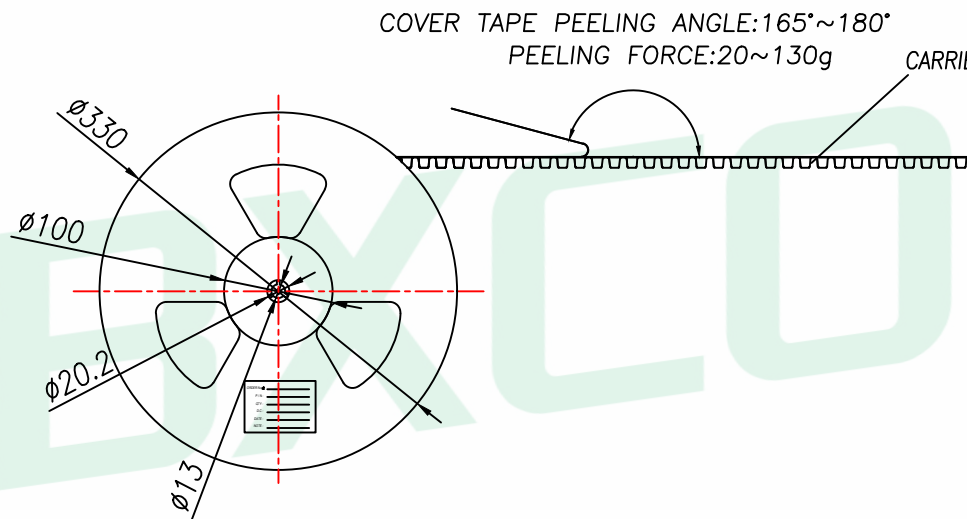
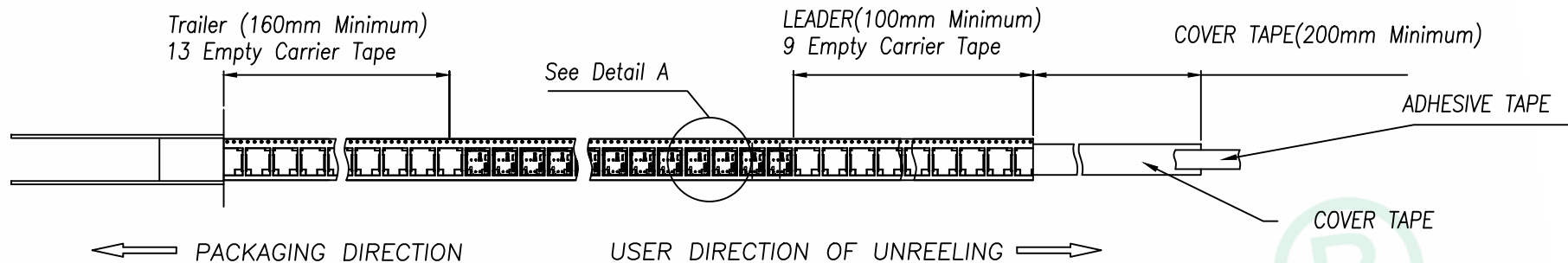
PIIN/NO	ASSIGNMENT
C1	VCC
C2	RST
C3	CLK
CD	Detect Switch
C5	GND
C6	VPP
C7	I/O

GENERAL TOLERANCE		DONGGUAN BAOXUN PRECISION TECHNOLOGY CO., LTD			
DIM.	TOL.	TITLE: NANO SIM CARD 1.37H PUSH PUSH 有柱			
x.	±0.35	DWG. NO.:	NANO-7P-H137		CHECKED: MAX
x.x	±0.15	PART NO.:	NANO-7P-H137		DRAWN: ELLA
x.xx	±0.10	UNIT:	mm	SCALE:	none
GENERAL ANGLE:	±2°	SHEET:	1 of 1	DWG. SIZE:	A4
x.°	±1°	LAYER:	bxconn		
x.x°	±1°	APPROVED:	WILL		
x.xx°	±0.5°				



**BXCONN**<sup>®</sup>



A		B		C		D		E	
REV.	DESCRIPTION				ECN NO.	NAME	DATE		



1	NANO-7P-H137	1500	10		15000	350X350X340
ITEM	PRODUCT NO	QTY/REEL	REEL/CARTON	Kg/CARTON	QTY/CARTON	CARTON SIZE

GENERAL TOLERANCE		DONGGUAN BAOXUN PRECISION TECHNOLOGY CO., LTD				BXCONN <sup>®</sup>		
DIM.	TOL.	TITLE: NANO SIM CARD 1.37H PUSH PUSH 有柱						
x.	±0.35	DWG. NO.: NANO-7P-H137		CHECKED: MAX				
x.x	±0.15	PART NO.: NANO-7P-H137		DRAWN: ELLA				
x.xx	±0.10	UNIT: mm		SCALE: none	SHEET: 1 of 1	DWG. SIZE: A4	LAYER: bxconn	APPROVED: WILL
GENERAL ANGLE:								
X°	±2°							
X.X°	±1°							
X.XX°	±0.5°							